

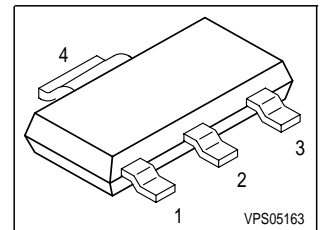
## SIPMOS<sup>®</sup> Small-Signal-Transistor

### Features

- N-Channel
- Enhancement mode
- Logic Level
- dv/dt rated

### Product Summary

Drain source voltage	$V_{DS}$	30	V
Drain-Source on-state resistance	$R_{DS(on)}$	0.05	$\Omega$
Continuous drain current	$I_D$	4.7	A



Type	Package	Ordering Code
BSP308	SOT-223	Q67000-S4011

Pin 1	Pin 2/4	PIN 3
G	D	S

### Maximum Ratings, at $T_j = 25\text{ °C}$ , unless otherwise specified

Parameter	Symbol	Value	Unit
Continuous drain current $T_A = 25\text{ °C}$ $T_A = 70\text{ °C}$	$I_D$	4.7 3.9	A
Pulsed drain current $T_A = 25\text{ °C}$	$I_D \text{ puls}$	18.8	
Reverse diode dv/dt $I_S = 4.7\text{ A}$ , $V_{DS} = 20\text{ V}$ , $di/dt = 200\text{ A}/\mu\text{s}$ , $T_{jmax} = 150\text{ °C}$	dv/dt	6	kV/ $\mu\text{s}$
Gate source voltage	$V_{GS}$	$\pm 20$	V
Power dissipation $T_A = 25\text{ °C}$	$P_{tot}$	1.8	W
Operating and storage temperature	$T_j, T_{stg}$	-55...+150	$^{\circ}\text{C}$
IEC climatic category; DIN IEC 68-1		55/150/56	

**Thermal Characteristics**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Characteristics</b>					
Thermal resistance, junction - soldering point	$R_{thJS}$	-	-	25	K/W
SMD version, device on PCB:	$R_{thJA}$				K/W
@ min. footprint		-	-	110	
@ 6 cm <sup>2</sup> cooling area <sup>1)</sup>		-	-	70	

**Electrical Characteristics, at  $T_j = 25\text{ °C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Static Characteristics</b>					
Drain- source breakdown voltage $V_{GS} = 0\text{ V}$ , $I_D = 250\text{ }\mu\text{A}$	$V_{(BR)DSS}$	30	-	-	V
Gate threshold voltage, $V_{GS} = V_{DS}$ $I_D = 20\text{ }\mu\text{A}$	$V_{GS(th)}$	1.2	1.6	2	
Zero gate voltage drain current $V_{DS} = 30\text{ V}$ , $V_{GS} = 0\text{ V}$ , $T_j = 25\text{ °C}$ $V_{DS} = 30\text{ V}$ , $V_{GS} = 0\text{ V}$ , $T_j = 125\text{ °C}$	$I_{DSS}$	-	0.1	1	$\mu\text{A}$
Gate-source leakage current $V_{GS} = 20\text{ V}$ , $V_{DS} = 0\text{ V}$	$I_{GSS}$	-	10	100	nA
Drain-Source on-state resistance $V_{GS} = 4.5\text{ V}$ , $I_D = 3.9\text{ A}$	$R_{DS(on)}$	-	0.05	0.075	$\Omega$
Drain-Source on-state resistance $V_{GS} = 10\text{ V}$ , $I_D = 4.7$	$R_{DS(on)}$	-	0.03	0.05	$\Omega$

<sup>1</sup>Device on 40mm\*40mm\*1.5mm epoxy PCB FR4 with 6cm<sup>2</sup> (one layer, 70  $\mu\text{m}$  thick) copper area for drain connection. PCB is vertical without blown air.

**Electrical Characteristics, at  $T_j = 25\text{ °C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Dynamic Characteristics</b>					
Transconductance $V_{DS} \geq 2 \cdot I_D \cdot R_{DS(on)max}$ , $I_D = 3.9\text{ A}$	$g_{fs}$	6.1	8.8	-	S
Input capacitance $V_{GS} = 0\text{ V}$ , $V_{DS} = 25\text{ V}$ , $f = 1\text{ MHz}$	$C_{iss}$	-	400	500	pF
Output capacitance $V_{GS} = 0\text{ V}$ , $V_{DS} = 25\text{ V}$ , $f = 1\text{ MHz}$	$C_{oss}$	-	160	200	
Reverse transfer capacitance $V_{GS} = 0\text{ V}$ , $V_{DS} = 25\text{ V}$ , $f = 1\text{ MHz}$	$C_{rss}$	-	70	90	
Turn-on delay time $V_{DD} = 15\text{ V}$ , $V_{GS} = 4.5\text{ V}$ , $I_D = 3.9\text{ A}$ , $R_G = 15\text{ }\Omega$	$t_{d(on)}$	-	16	24	ns
Rise time $V_{DD} = 15\text{ V}$ , $V_{GS} = 4.5\text{ V}$ , $I_D = 3.9\text{ A}$ , $R_G = 15\text{ }\Omega$	$t_r$	-	30	45	
Turn-off delay time $V_{DD} = 15\text{ V}$ , $V_{GS} = 4.5\text{ V}$ , $I_D = 3.9\text{ A}$ , $R_G = 15\text{ }\Omega$	$t_{d(off)}$	-	16	24	
Fall time $V_{DD} = 15\text{ V}$ , $V_{GS} = 4.5\text{ V}$ , $I_D = 3.9\text{ A}$ , $R_G = 15\text{ }\Omega$	$t_f$	-	15	23	

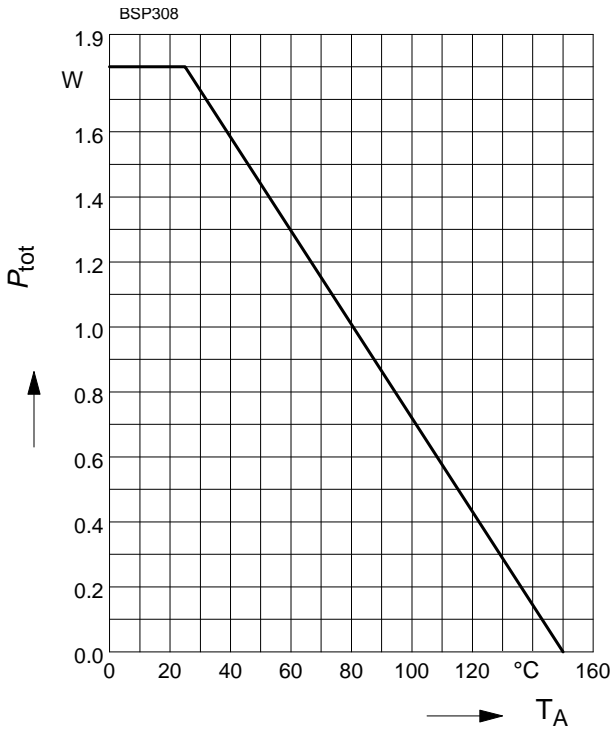
**Electrical Characteristics, at  $T_j = 25\text{ °C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Dynamic Characteristics</b>					
Gate to source charge $V_{DD} = 24\text{ V}, I_D = 4.7\text{ A}$	$Q_{gs}$	-	1.9	2.9	nC
Gate to drain charge $V_{DD} = 24\text{ V}, I_D = 4.7\text{ A}$	$Q_{gd}$	-	5.4	8.1	
Gate charge total $V_{DD} = 24\text{ V}, I_D = 4.7\text{ A}, V_{GS} = 0\text{ to }10\text{ V}$	$Q_g$	-	14.5	22	
Gate plateau voltage $V_{DD} = 24\text{ V}, I_D = 4.7\text{ A}$	$V_{(plateau)}$	-	3.1	-	V

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Reverse Diode</b>					
Inverse diode continuous forward current $T_A = 25\text{ °C}$	$I_S$	-	-	4.7	A
Inverse diode direct current,pulsed $T_A = 25\text{ °C}$	$I_{SM}$	-	-	18.8	
Inverse diode forward voltage $V_{GS} = 0\text{ V}, I_F = 4.7\text{ A}$	$V_{SD}$	-	0.84	1.1	V
Reverse recovery time $V_R = 15\text{ V}, I_F = I_S, di_F/dt = 100\text{ A}/\mu\text{s}$	$t_{rr}$	-	38.4	57.6	ns
Reverse recovery charge $V_R = 15\text{ V}, I_F = I_S, di_F/dt = 100\text{ A}/\mu\text{s}$	$Q_{rr}$	-	22.3	33.5	nC

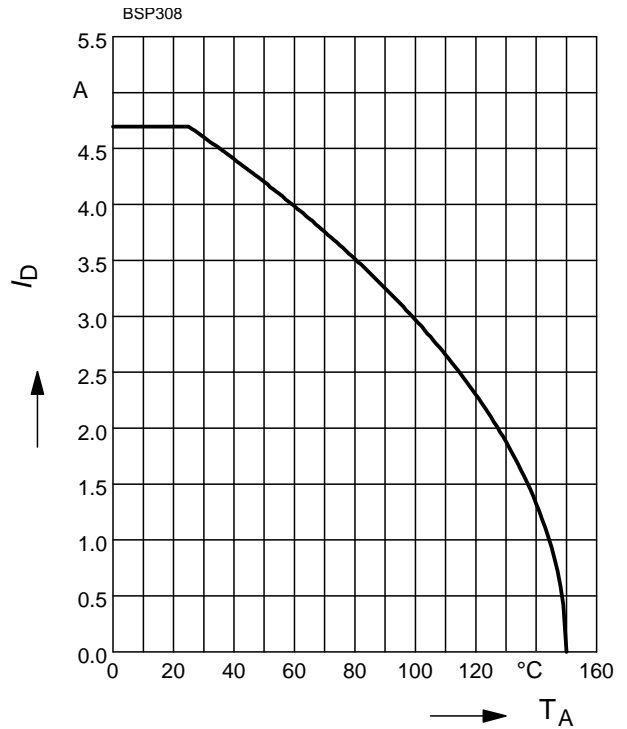
**Power Dissipation**

$$P_{tot} = f(T_A)$$



**Drain current**

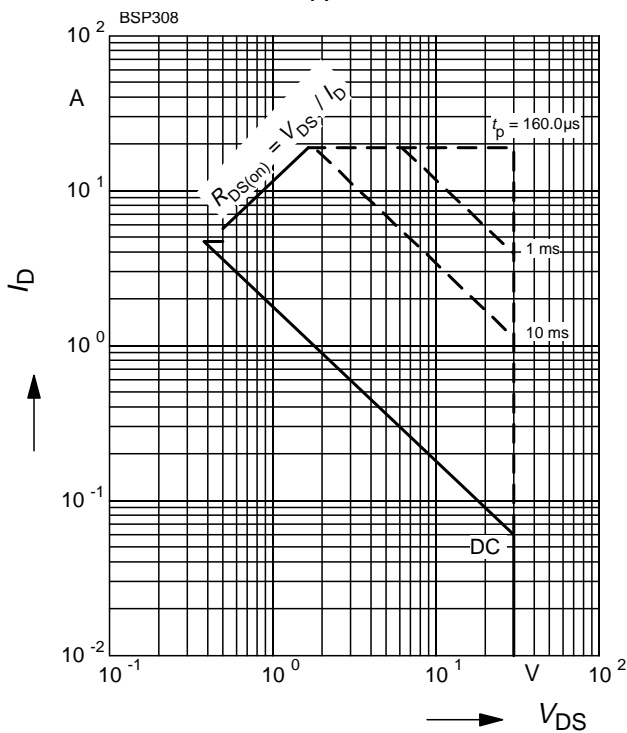
$$I_D = f(T_A)$$



**Safe operating area**

$$I_D = f(V_{DS})$$

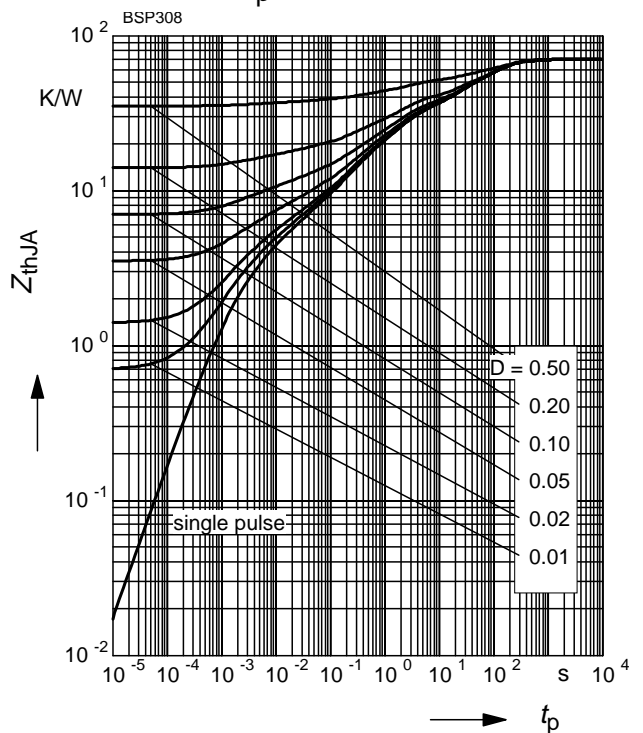
parameter :  $D = 0$  ,  $T_A = 25\text{ °C}$



**Transient thermal impedance**

$$Z_{thJA} = f(t_p)$$

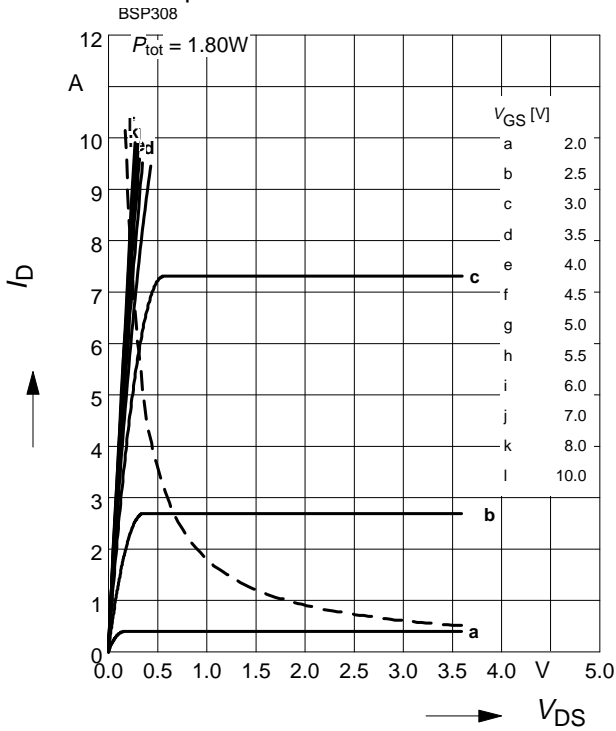
parameter :  $D = t_p/T$



**Typ. output characteristics**

$$I_D = f(V_{DS})$$

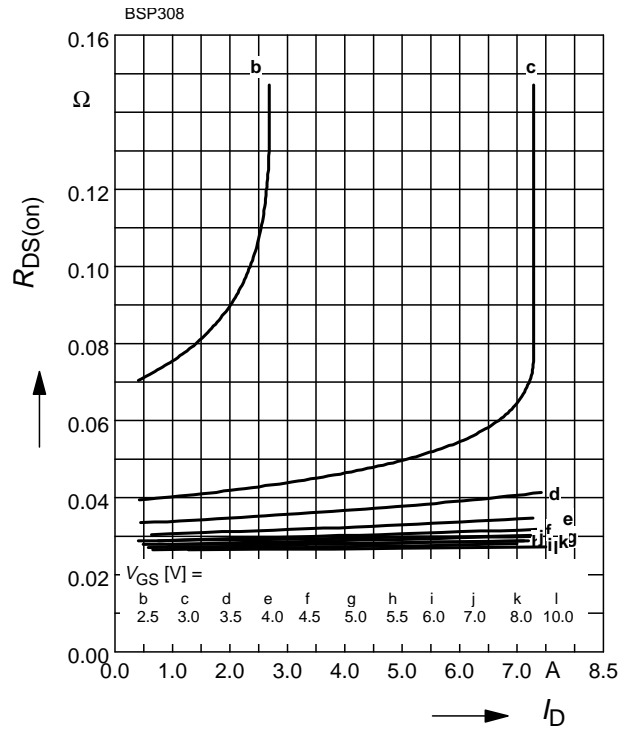
parameter:  $t_p = 80 \mu s$



**Typ. drain-source-on-resistance**

$$R_{DS(on)} = f(I_D)$$

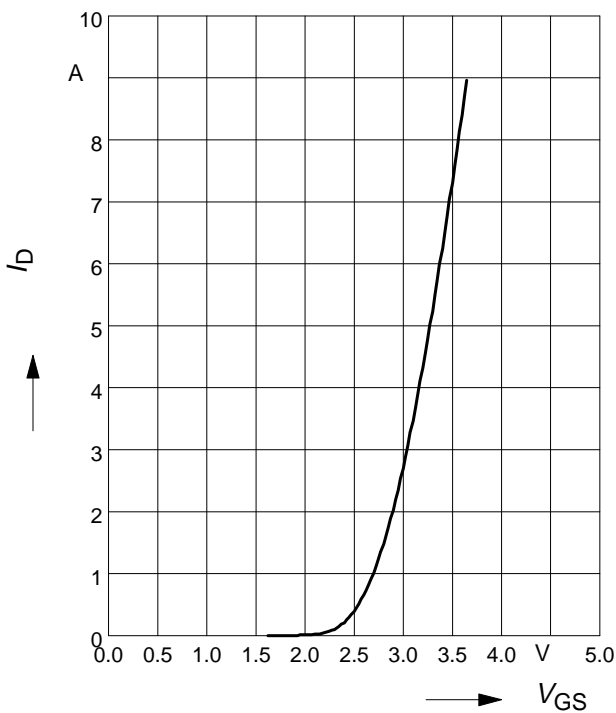
parameter:  $V_{GS}$



**Typ. transfer characteristics  $I_D = f(V_{GS})$**

$$V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$$

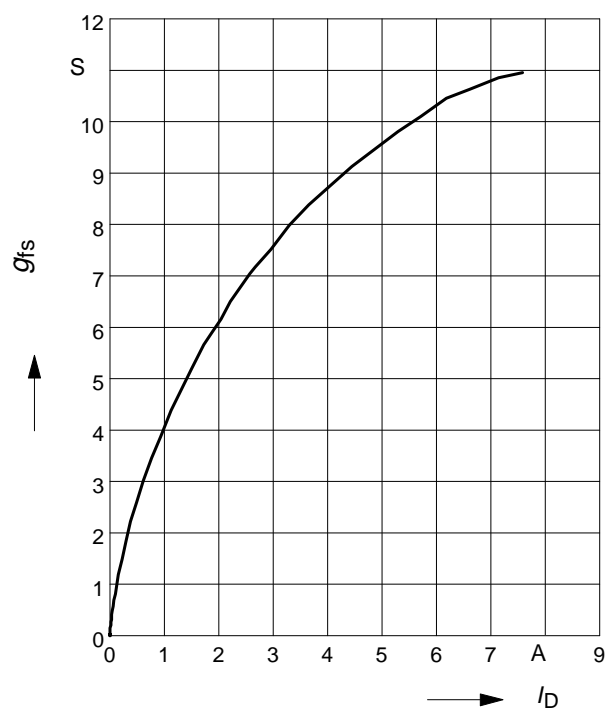
parameter:  $t_p = 80 \mu s$



**Typ. forward transconductance**

$$g_{fs} = f(I_D); T_j = 25^\circ C$$

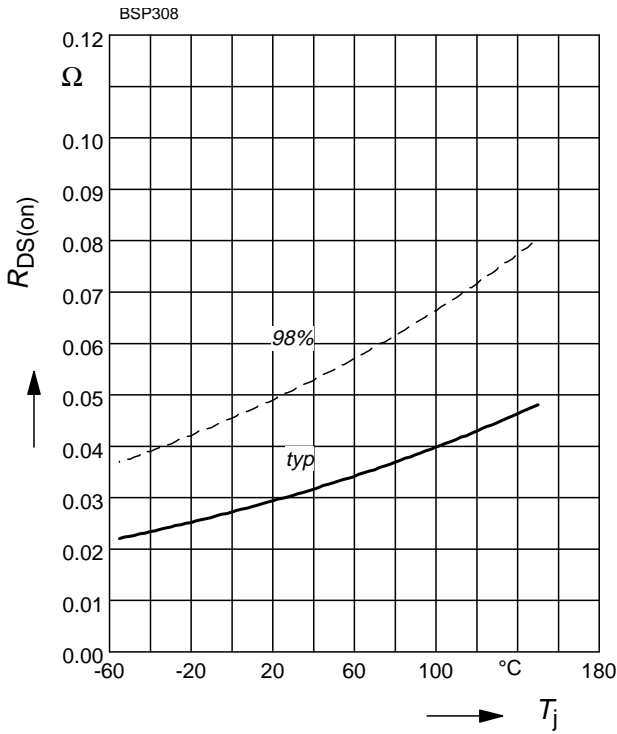
parameter:  $g_{fs}$



**Drain-source on-resistance**

$$R_{DS(on)} = f(T_j)$$

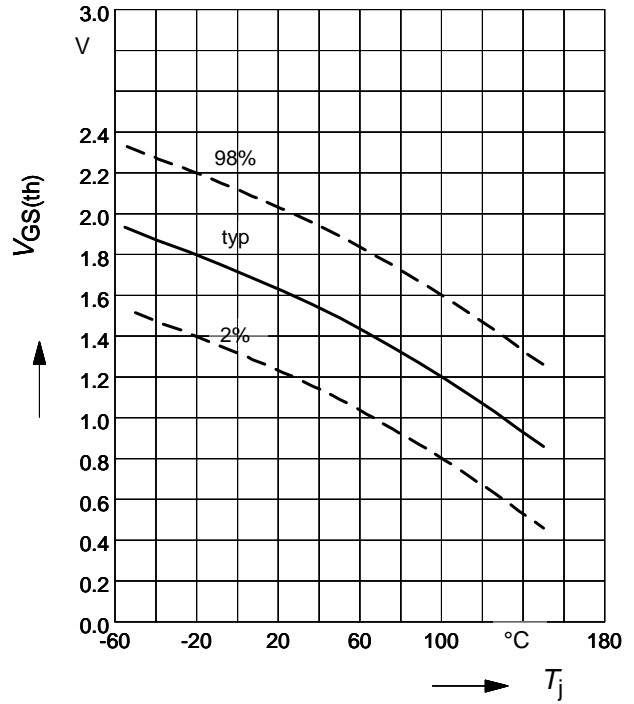
parameter:  $I_D = 4.7$ ,  $V_{GS} = 10$  V



**Gate threshold voltage**

$$V_{GS(th)} = f(T_j)$$

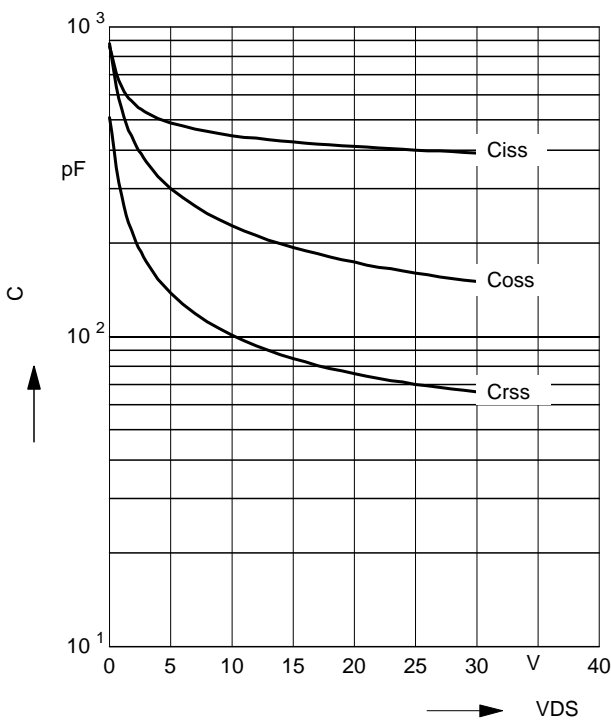
parameter:  $V_{GS} = V_{DS}$ ,  $I_D = 20 \mu A$



**Typ. capacitances**

$$C = f(V_{DS})$$

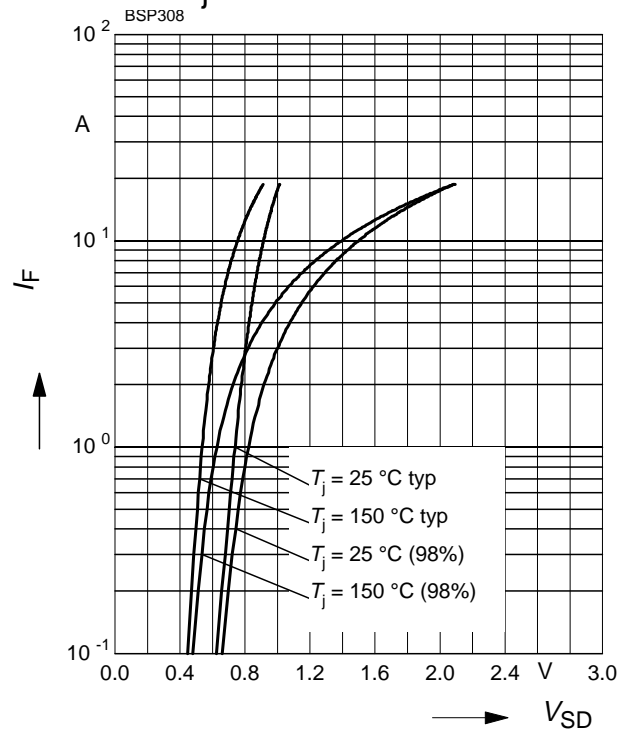
parameter:  $V_{GS} = 0$  V,  $f = 1$  MHz



**Forward characteristics of reverse diode**

$$I_F = f(V_{SD})$$

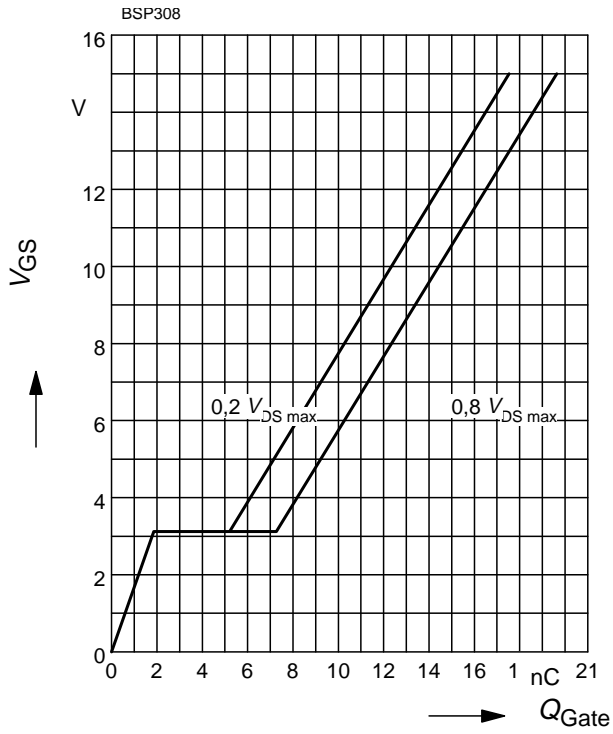
parameter:  $T_j$ ,  $t_p = 80 \mu s$



**Typ. gate charge**

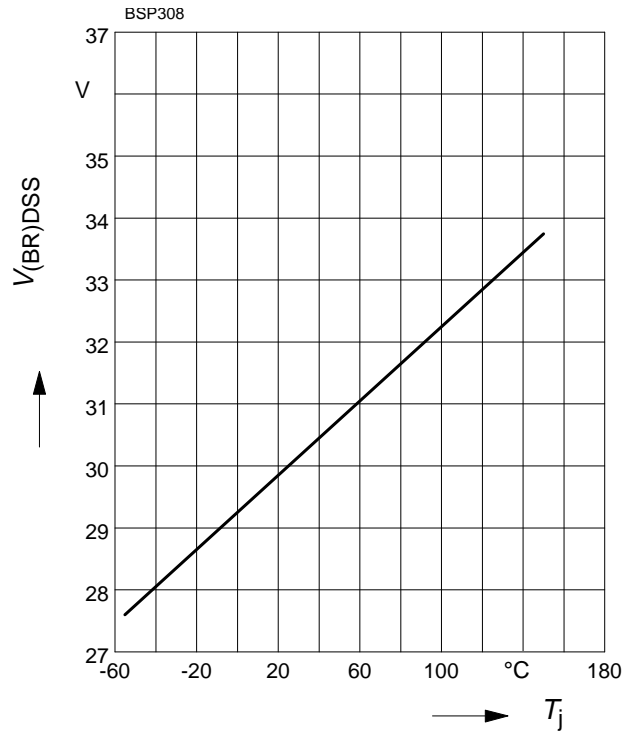
$$V_{GS} = f(Q_{Gate})$$

parameter:  $I_D = 4.7$  A pulsed



**Drain-source breakdown voltage**

$$V_{(BR)DSS} = f(T_j)$$





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